IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				terials and	ials and Mfg Information			
upplier	Information														
Company name*			Company uni	Company unique ID			Unique ID Authority				Respo	Response Date*			
nsemi											2023-0	2023-06-08			
Contact Na	ame	Title - Contact			I	Phone - Contact*				Email	Email - Contact*				
Product-E	Inv-Stewards	Product Enviro Compliance]	NA				Produ	Product-Env-Stewards@onsemi.com				
uthorized	l Representative*	Title - Representative			I	Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Produ	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Ite		n Number Mfr Item Name				Effective Date	Version Manufacturing Site			Weight*	UOM	Unit Type		
		NCP333 G	335ADM150R2 ANA 500MA ANY C		Y CAP LDO		2023-06-08		MY1			31.93	mg	Each	
Ianufac	cturing Proccess Informa	ation													
	Terminal Plating / Grid Array M	Ferminal Base Alloy J-STD-020 MSI		Rating	Peak Process Body Temperature Max Time		e Max Time at P	eak Temper	ature Numb	er of Reflow Cyc	cles				
Matte Tin (Sn) - annealed		CU Alloy 1			260 C 30		seco	seconds 3							
omments															
vel 1 - ma	aximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
or more i	nformation regarding materia	l composition	please refer to	page 3					· · · · · · · · · · · · · · · · · · ·			· · · · · · · · · · · · · · · · · · ·			

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.32	mg	Supplier	Silicon (Si)	7440-21-3		1.32	mg
Die Attach	0.91	mg		Epoxy resin	proprietary data		0.0228	mg
			Supplier	Silver (Ag)	7440-22-4		0.769	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0228	mg
			Supplier	Inorganic filler	Proprietary Data		0.0228	mg
			Supplier	Dicyandiamine	461-58-5		0.0046	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0682	mg
Lead Frame	14.26	mg	Supplier	Silver (Ag)	7440-22-4		0.3565	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0143	mg
			Supplier	Iron (Fe)	7439-89-6		0.3422	mg
			Supplier	Copper (Cu)	7440-50-8		13.547	mg
Mold Compound-Black	14.96	mg		Epoxy resin	proprietary data		0.748	mg
			Supplier	Phenolic Resin	Proprietary Data		0.748	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.2992	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0748	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		13.09	mg
Plating	0.38	mg	Supplier	Tin (Sn)	7440-31-5		0.38	mg
Wire Bond	0.1	mg	Supplier	Palladium (Pd)	7440-05-3		0.001	mg
			Supplier	Copper (Cu)	7440-50-8		0.099	mg